



DATE: August 14, 2024

PCN #: 2694

PCN Title: Additional Wafer Sources and Transfer of Wafer Manufacturing Site for Select Discrete Automotive Products – Automotive

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of notification by contacting your local Diodes sales representative. If you require samples for evaluation purposes, please submit a corresponding request within 30 days as well. Otherwise, samples may not be built prior to the implementation of the announced change(s).

The change(s) announced in this PCN will not be implemented prior to the target implementation date, i.e. 90 days from the stated notification date, unless Diodes receives written customer approval before that date.

Previously agreed upon customer specific product and/or process change requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE

PCN-2694-REV1

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
August 14, 2024	November 12, 2024	Discrete Semiconductor	Additional Wafer Source, Metallization System	2694
TITLE				
Additional Wafer Sources and Transfer of Wafer Manufacturing Site for Select Discrete Automotive Products				
DESCRIPTION OF CHANGE				
<p>This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes Incorporated has qualified the following wafer source changes for select discrete automotive products listed below.</p> <ul style="list-style-type: none">• Diodes internal wafer fabrication source (JKFAB) in Hsinchu, Taiwan as additional wafer source, and Diodes internal assembly and test site (SAT) located in Shanghai, China for processing wafer back metal (BM).• Diodes internal wafer fabrication source (SFAB2) in Shanghai, China as additional wafer source with wafer top metal (TM) and back metal (BM) being processed at Diodes internal CAT site. Wafer top metal will be changed from TiNiAg to NiAu at CAT.• Diodes internal wafer fabrication source WX1 in WuXi, China as new wafer source. Affected products will be transferred from Diodes internal wafer fabrication source SSEC in Shanghai, China, which is planned to be closed by 31 August 2024. <p>Full electrical characterization and reliability testing have been completed on representative part numbers to ensure there is no change to product reliability, device functionality or electrical specifications in the datasheet.</p> <p>There will be no change to the Form, Fit, or Function of affected products.</p>				
IMPACT				
No change in datasheet parameters				
PRODUCTS AFFECTED				
Table 1 – Affected part list to add JKFAB as additional wafer source, and add SAT for BM Table 2 – Affected part list to add SFAB2 as additional wafer source, and add CAT for TM and BM Table 3 – Affected part list to transfer to WX1 FAB as new wafer source				
WEB LINKS				
Manufacturer’s Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/			
For More Information Contact:	https://www.diodes.com/about/contact-us/contact-sales/			
Data Sheet:	https://www.diodes.com/catalog/			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days from the notification date of this PCN, all changes described in this announcement are considered approved.				

Table 1 - Affected part list to add JKFAB as additional wafer source, and add SAT for BM					
BZT52C30Q-7-F	BZT52C36SQ-7-F	BZX84C30Q-13-F	BZX84C43Q-13-F	BZX84C51Q-7-F	MMSZ5257BQ-7-F
BZT52C30SQ-7-F	BZT52C39Q-7-F	BZX84C30Q-7-F	BZX84C43Q-7-F	MMBZ5257BQ-7-F	MMSZ5258BQ-13-F
BZT52C33Q-7-F	BZT52C43Q-7-F	BZX84C33Q-13-F	BZX84C47Q-13-F	MMSZ5255BQ-7-F	MMSZ5258BQ-7-F
BZT52C33SQ-7-F	BZT52C47Q-7-F	BZX84C33Q-7-F	BZX84C47Q-7-F	MMSZ5256BQ-7-F	MMSZ5259BQ-7-F
BZT52C36Q-7-F	BZT52C51Q-7-F	BZX84C36Q-7-F			

Table 2 - Affected part list to add SFAB2 as additional wafer source, and add CAT for TM and BM					
SBR140S1FQ-7	SBR1U150SAQ-13				

Table 3 - Affected part list to transfer to WX1 FAB as new wafer source					
RS1MEWFQ-7	RS1MSWFMQ-7				